MUR6060PT

Rev.E Mar.-2016

DATA SHEET

/ Descriptions

TO-3P

Ultrafast Recovery Diode in a TO-3P Plastic Package.

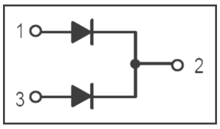
/ Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

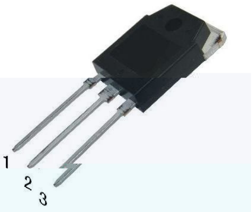
/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode

/ Equivalent Circuit



/ Pinning

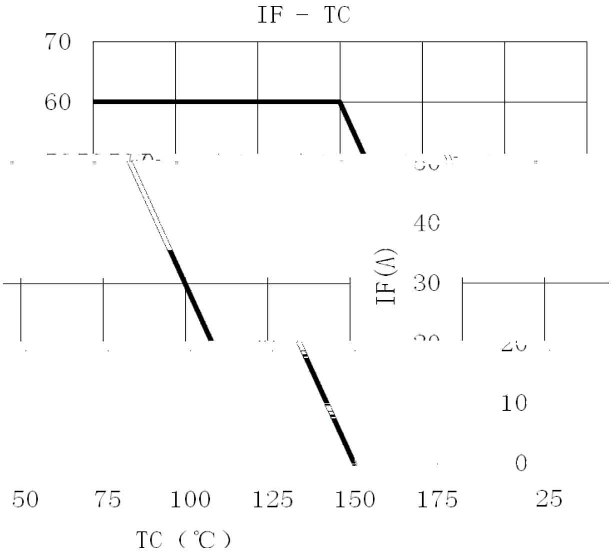


PIN1	Anode	PIN2	Cathode	PIN 3	Anode

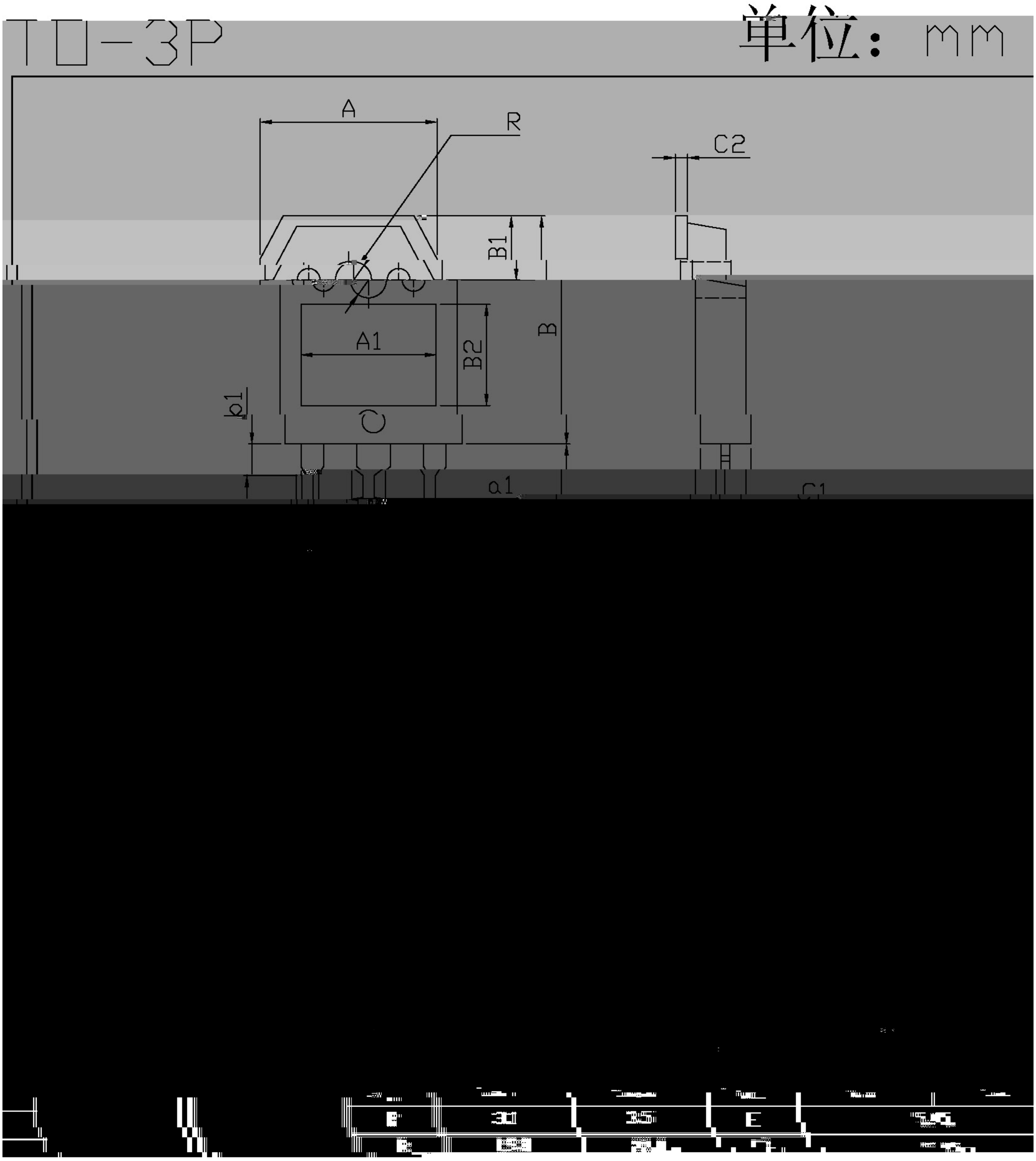
/ h_{FE} Classifications & Marking

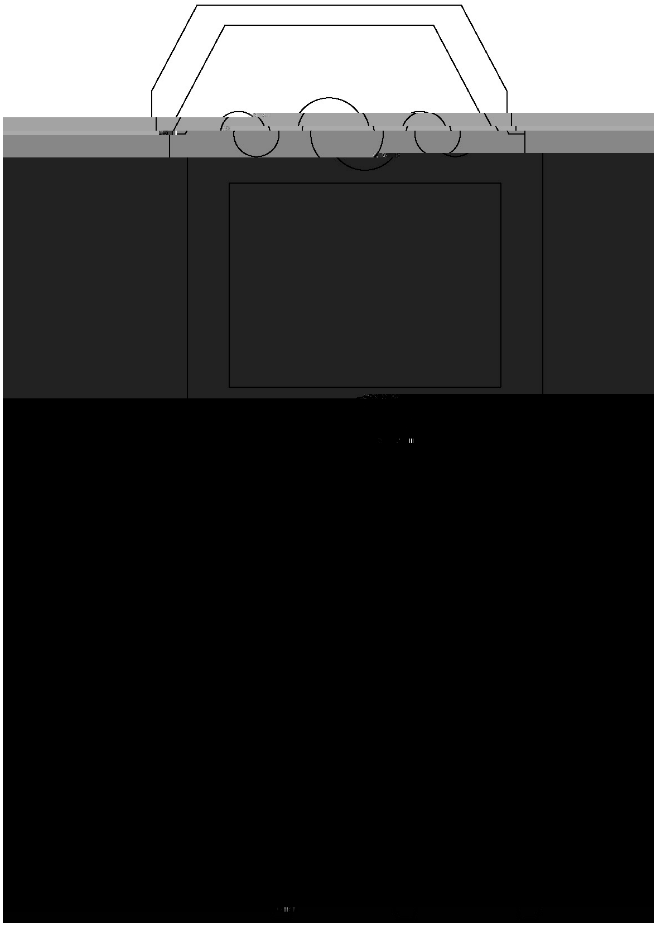
See Marking Instructions

/ Electrical Characteristic Curve



/ Package Dimensions





( ) / Temperature Profile for Dip Soldering(Pb-Free)

Note:

1 25 150 60 90sec;
2 255±5 5±0.5sec;
3 2 10 /sec.

1.Preheating:25~150 , Time:60~90sec.
2.Peak Temp.:255±5 , Duration:5±0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec.

Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type	Units					Dimension		(unit mm^3)
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	In8T	